3.0mmx1.0mm RIGHT ANGLE PHOTOTRANSISTOR

Part Number: KPA-3010P3C

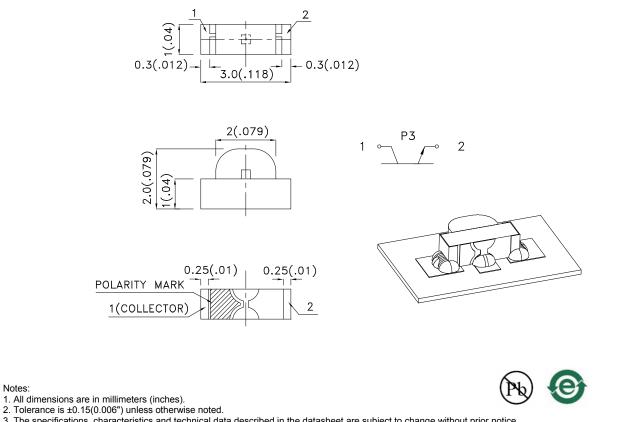
Features

- 3.0mmx1.0mm right angle SMT LED, 2.0mm thickness.
- Mechanically and spectrally matched to the infrared emitting
- LED lamp.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability.
- RoHS compliant.

Description

Made with NPN silicon phototransistor chips.

Package Dimensions



The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
The device has a single mounting surface. The device must be mounted according to the specifications.

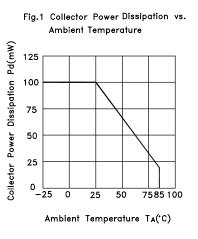
SPEC NO: DSAB1638 APPROVED: WYNEC REV NO: V.14 CHECKED: Allen Liu DATE: AUG/14/2013 DRAWN: D.N.Huang PAGE: 1 OF 5 ERP: 1203000589

Electrical / Optical Characteristics at TA=25°C

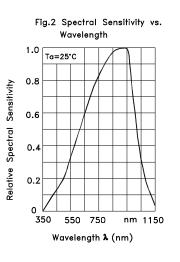
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
VBR CEO	Collector-to-Emitter Breakdown Voltage	30			V	Ic=100uA Ee=0mW/c m
VBR ECO	Emitter-to-Collector Breakdown Voltage	5			V	l∈=100uA Ee=0mW/c mঁ
VCE (SAT)	Collector-to-Emitter Saturation Voltage			0.8	V	lc=2mA Ee=20mW/c mໍ
I CEO	Collector Dark Current			100	nA	Vce=10V Ee=0mW/c m
Tr	Rise Time (10% to 90%)		15		us	Vce = 5V Ic=1mA RL=1000Ω
Tf	Fall Time (90% to 10%)		15		us	
I (ON)	On State Collector Current	0.2	0.4		mA	Vce = 5V Ee=1mW/c m ^² λ=940nm

Absolute Maximum Ratings at TA=25°C

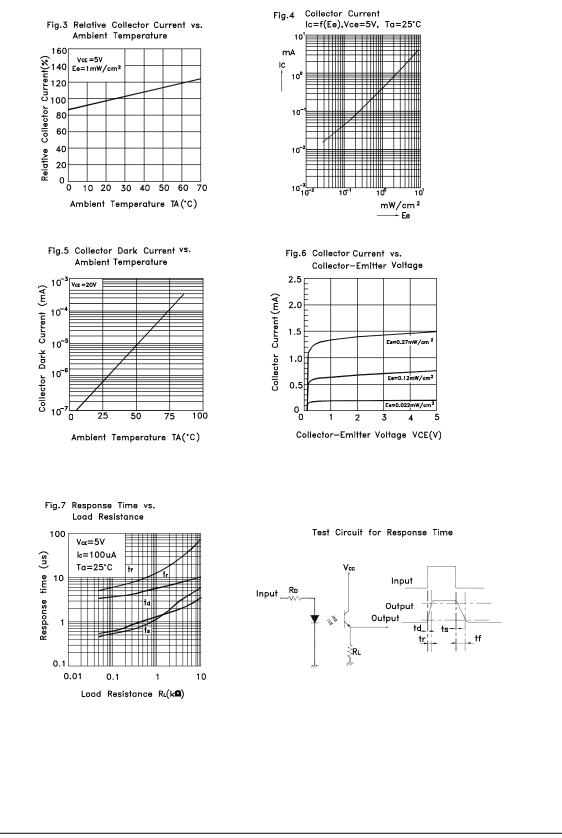
Parameter	Max.Ratings		
Collector-to-Emitter Voltage	30V		
Emitter-to-Collector Voltage	5V		
Power Dissipation at (or below) 25°C Free Air Temperature	100mW		
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		



Typical Electro-Optical Characteristics Curves



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KPA-3010P3C Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product. Reflow Soldering Profile For Lead-free SMT Process. 300 (°C) 10 s max 260°C max 250 230°C 4°C/s 4°C/s max 200 150~180° 4°C/s max 150 Temperature 60~120 30~50s 100 50 25°C 0 ō 50 100 150 200 250 300 (sec) Tim NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less. **Reel Dimension Recommended Soldering Pattern** (Units : mm; Tolerance: ± 0.1) 12[0.472]±0.5 0.9 0.9 õ 1<u>8[.7</u>09]±0.2 R6.5[.256]± ¢178[7.008]±1 ¢60[2.362] ø56[2.205] 2 ŝ Ċ 1.5 1.5 5.0 Ŕ36[1 9[0.354]±0.2 **Tape Specifications** (Units : mm) TAPE 4.0±0.05 1.75±0.1 2.0 ± 0.05 ø1.5 +0.1 4.0±0.1 0.23±0.05 1.2 ± 0.1 .05 8.0±0.2 3.5±0.

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